# **Hex D Master-Slave Flip-Flop**

The MC10H176 contains six master slave type D flip-flops with a common clock. This MECL 10H part is a functional/pinout duplication of the standard MECL 10K family part, with 100% improvement in clock frequency and propagation delay and no increase in power-supply current.

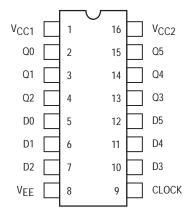
- Propagation Delay, 1.7 ns Typical
- Power Dissipation, 460 mW Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

#### **CLOCKED TRUTH TABLE**

С	Q	Q <sub>n+1</sub>
L	Х	Qn
H *	L	L
H *	Н	Н

\* A clock H is a clock transition from a low to a high state.

#### DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



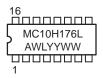
#### ON Semiconductor

http://onsemi.com

#### MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

#### **ORDERING INFORMATION**

Device	Package	Shipping
MC10H176L	CDIP-16	25 Units/Rail
MC10H176P	PDIP-16	25 Units/Rail
MC10H176FN	PLCC-20	46 Units/Rail

#### **MAXIMUM RATINGS**

Symbol	Characteristic	Rating	Unit	
VEE	Power Supply (V <sub>CC</sub> = 0)	-8.0 to 0	Vdc	
VI	Input Voltage (V <sub>CC</sub> = 0)	0 to VEE	Vdc	
l <sub>out</sub>	Output Current – Continuous – Surge	50 100	mA	
TA	Operating Temperature Range	0 to +75	°C	
T <sub>stg</sub>	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C °C	

### **ELECTRICAL CHARACTERISTICS** ( $V_{EE} = -5.2 \text{ V} \pm 5\%$ ) (See Note 1.)

		<b>0</b> °		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙE	Power Supply Current	_	123	-	112	-	123	mA
linH	Input Current High Pins 5,6,7,10,11,12 Pin 9	- -	425 670		265 420	- -	265 420	μΑ
linL	Input Current Low	0.5	_	0.5	-	0.3	-	μΑ
Voн	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V <sub>OL</sub>	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
VIH	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V <sub>IL</sub>	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

#### **AC PARAMETERS**

t <sub>pd</sub>	Propagation Delay	0.9	2.1	0.9	2.2	1.0	2.4	ns
t <sub>set</sub>	Set-up Time	1.5	-	1.5	ı	1.5	-	ns
thold	Hold Time	0.9	-	0.9	ı	1.0	-	ns
t <sub>r</sub>	Rise Time	0.5	1.8	0.5	1.9	0.5	2.0	ns
t <sub>f</sub>	Fall Time	0.5	1.8	0.5	1.9	0.5	2.0	ns
ftog	Toggle Frequency	250	_	250	-	250	-	MHz

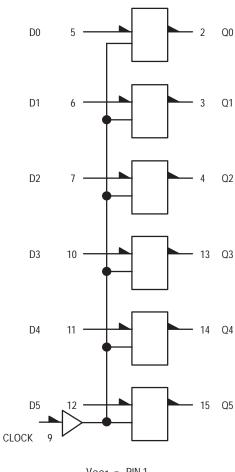
<sup>1.</sup> Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts.

#### **APPLICATION INFORMATION**

The MC10H176 contains six high-speed, master slave type "D" flip-flops. Data is entered into the master when the clock is low. Master-to-slave data transfer takes place on the positive-going Clock transition. Thus, outputs may

change only on a positive—going Clock transition. A change in the information present at the data (D) input will not affect the output information any other time due to the master—slave construction of this device.

#### **LOGIC DIAGRAM**

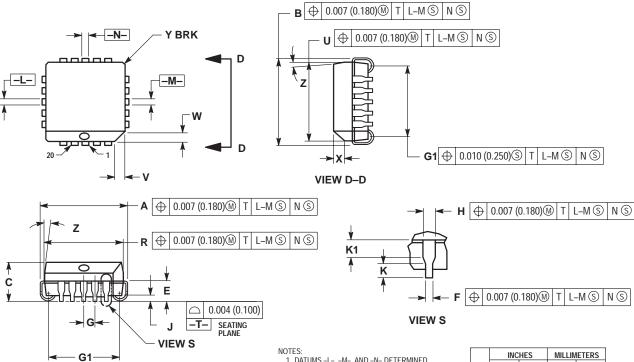


 $V_{CC1}$  = PIN 1  $V_{CC2}$  = PIN 16  $V_{EE}$  = PIN 8

#### **PACKAGE DIMENSIONS**

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

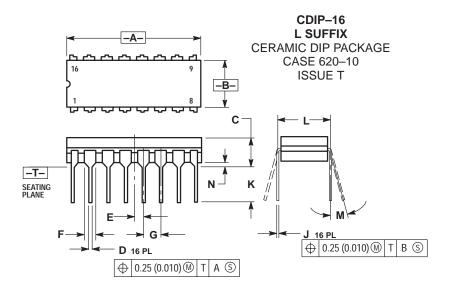
⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
   WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTENSIVE SOLUTION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS	
DIM	MIN			MAX	
A	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27 BSC		
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Х	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

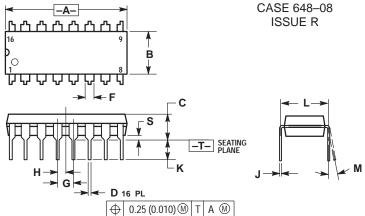
#### **PACKAGE DIMENSIONS**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS		
DIM	MIN	MIN MAX		MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Ε	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

#### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

# **Notes**

# **Notes**

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